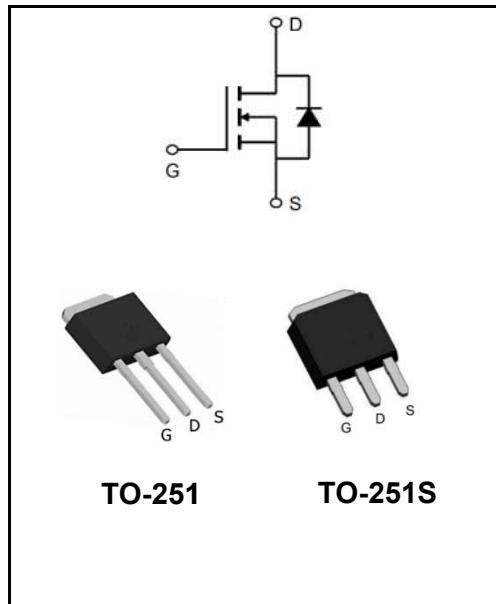


30V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

| | |
|-------------------------------|------------------------|
| I_D | 100A |
| V_{DSS} | 30V |
| $R_{DS(on)-typ}(@V_{GS}=10V)$ | < 6.5mΩ (Type: 4.5 mΩ) |


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

| Part Number | Package | Marking | Pack |
|--------------|---------|---------------------|--------------|
| YFW100N03AMJ | TO-251 | YFW 100N03AMJ XXXXX | 4000PCS/Tape |
| YFW100N03AMJ | TO-251S | YFW 100N03AMJ XXXXX | 4000PCS/Tape |

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

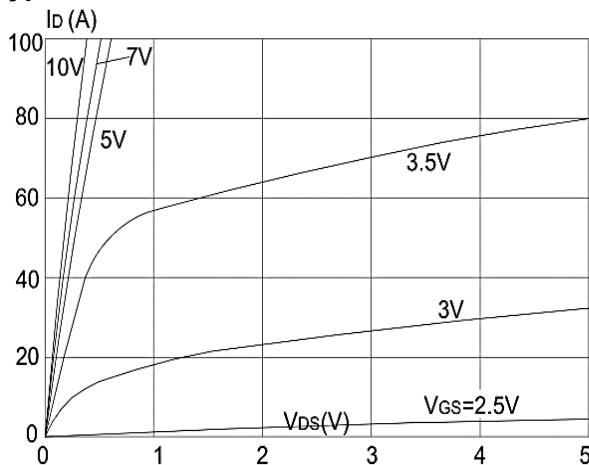
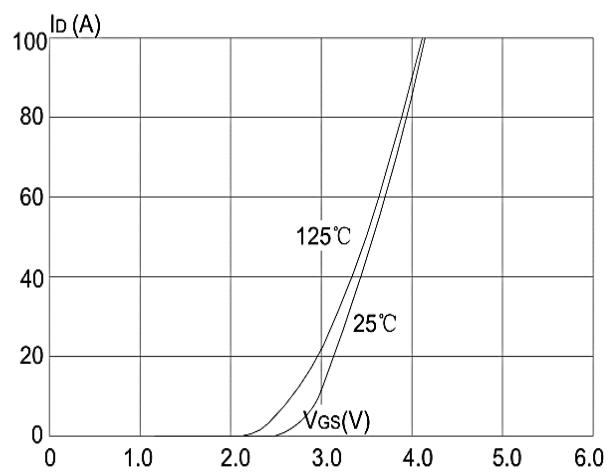
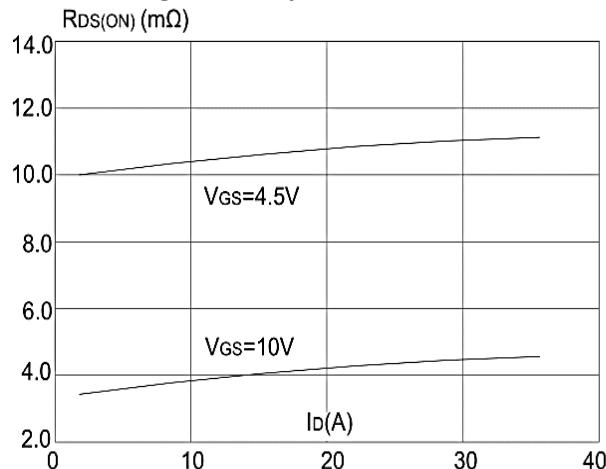
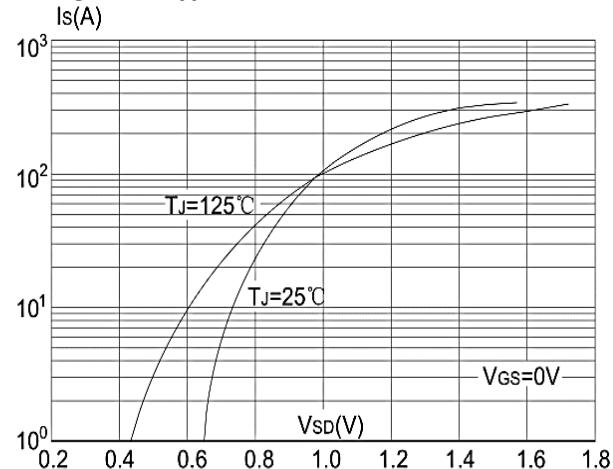
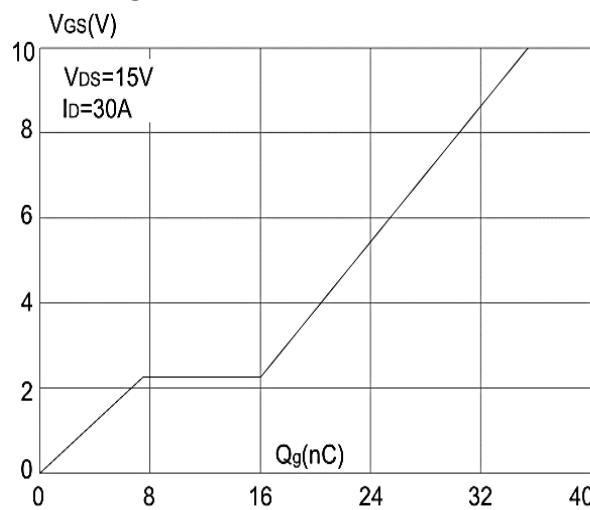
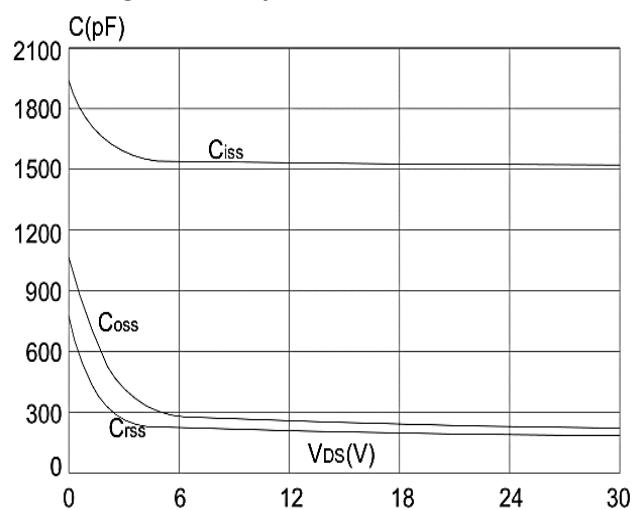
| Characteristics | Symbols | Value | Units |
|---|-----------------|-------------|-------|
| Drain-Source Voltage | V_{DS} | 30 | V |
| Gate - Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=25^\circ\text{C}$ | I_D | 100 | A |
| Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=75^\circ\text{C}$ | I_D | 55 | A |
| Pulsed Drain Current ² | I_{DM} | 240 | A |
| Single Pulse Avalanche Energy ³ | E_{AS} | 56 | mJ |
| Avalanche Current | I_{AS} | 15 | A |
| Total Power Dissipation ⁴ @ $T_c=25^\circ\text{C}$ | P_D | 46 | W |
| Total Power Dissipation ⁴ @ $T_A=25^\circ\text{C}$ | P_D | 2.72 | W |
| Storage Temperature Range | T_{STG} | -55 to +175 | °C |
| Operating Junction Temperature Range | T_J | -55 to +175 | °C |
| Thermal Resistance, Junction-to-Ambient ¹ | $R_{\theta JA}$ | 62 | °C/W |
| Thermal Resistance Junction-Case ¹ | $R_{\theta JC}$ | 2.72 | °C/W |

Maximum Ratings at Tc=25°C unless otherwise specified

| Characteristics | Test Condition | Symbols | Min | Typ | Max | Units |
|--|---|---------------------|-----|------|------|-------|
| Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | V(BR)DSS | 30 | 32 | - | V |
| Zero Gate Voltage Drain Current | V _{DS} =30V, V _{GS} =0V | I _{DSS} | - | - | 1.0 | µA |
| Gate to Body Leakage Current | V _{GS} =±20V, V _{DS} =0V | I _{GSS} | - | - | ±100 | nA |
| Gate -Threshold Voltage | V _{DS} =V _{GS} , I _D =250uA | V _{GS(th)} | 1.0 | 1.5 | 2.5 | V |
| Static Drain-Source on-Resistance | V _{GS} =10V, I _D =30A | R _{DS(ON)} | - | 4.5 | 6.5 | mΩ |
| | V _{GS} =4.5V, I _D =20A | | - | 7.5 | 12 | |
| Input Capacitance | V _{DS} =15V V _{GS} =0V f=1.0MHz | C _{iss} | - | 1614 | - | pF |
| Output Capacitance | | C _{oss} | - | 245 | - | |
| Reverse Transfer Capacitance | | C _{rss} | - | 215 | - | |
| Total Gate Charge | V _{DS} =15V I _D =30A V _{GS} =10V | Q _g | - | 33.7 | - | nC |
| Gate-Source Charge | | Q _{gs} | - | 8.5 | - | |
| Gate-Drain("Miller") Charge | | Q _{gd} | - | 7.5 | - | |
| Turn-on delay time | V _{DS} =15V I _D =30A R _{GEN} =3Ω V _{GS} =10V | t _{d(on)} | - | 7.5 | - | ns |
| Turn-on Rise Time | | T _r | - | 14.5 | - | |
| Turn-Off Delay Time | | t _{d(OFF)} | - | 35.2 | - | |
| Turn-Off Fall Time | | t _f | - | 9.6 | - | |
| Maximum Continuous Drain to Source Diode Forward Current | I _s | - | - | - | 70 | A |
| Maximum Pulsed Drain to Source Diode Forward Current | I _{SM} | - | - | - | 280 | A |
| Drain to Source Diode Forward Voltage | V _{GS} =0V, I _s =30A | V _{SD} | - | - | 1.2 | V |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=15A
4. The power dissipation is limited by 175°C junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves
Typical Characteristics

Figure 1: Output Characteristics

Figure 2: Typical Transfer Characteristics

Figure 3: On-resistance vs. Drain Current

Figure 4: Body Diode Characteristics

Figure 5: Gate Charge Characteristics

Figure 6: Capacitance Characteristics

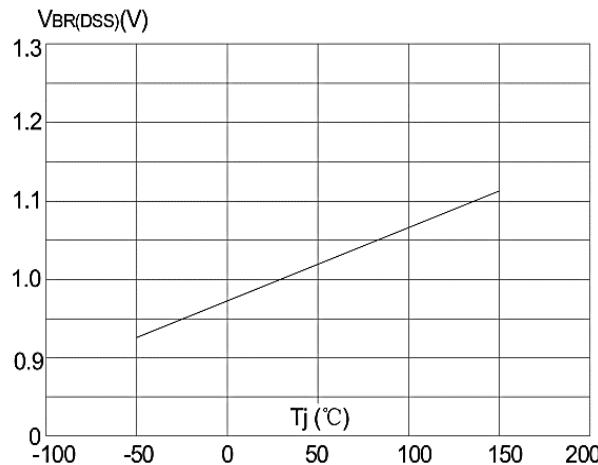
Ratings and Characteristic Curves


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

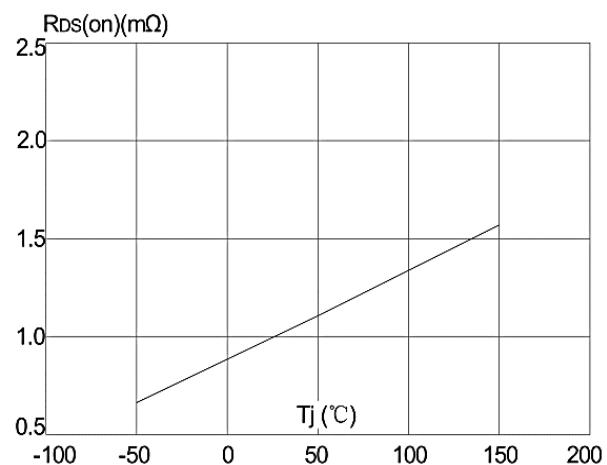


Figure 8: Normalized on Resistance vs Junction Temperature

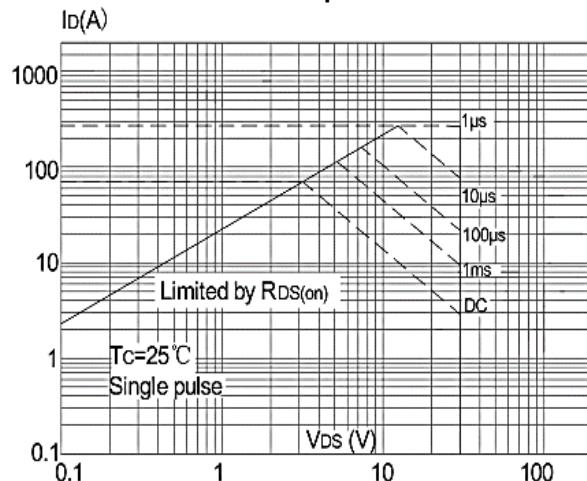


Figure 9: Maximum Safe Operating Area vs. Case Temperature

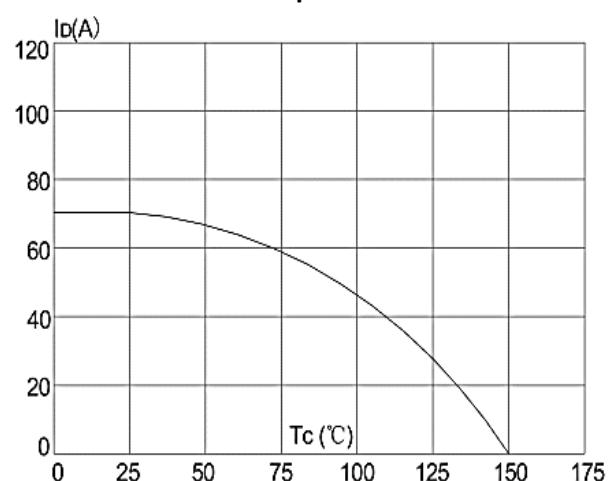


Figure 10: Maximum Continuous Drain Current

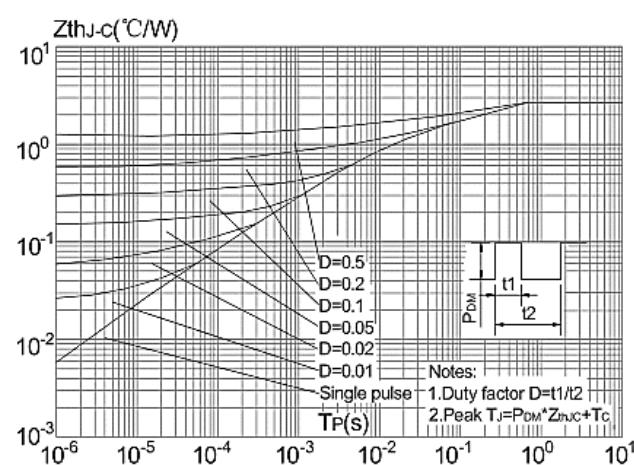
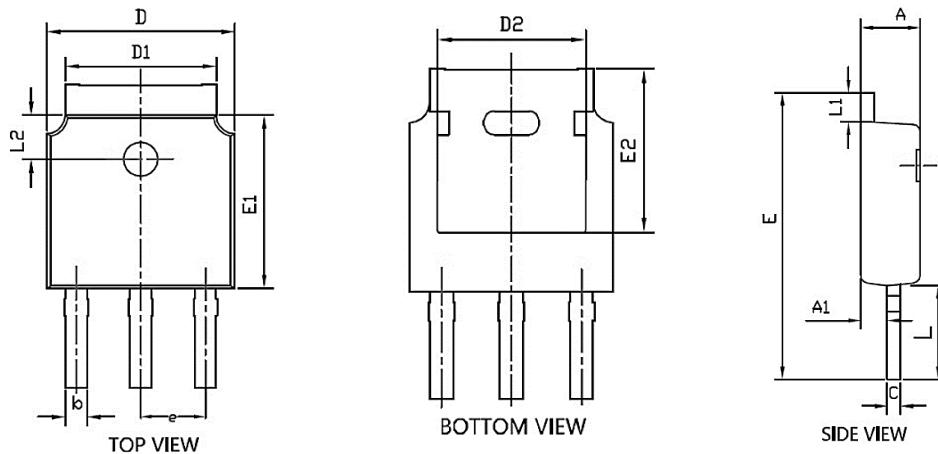


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ca

Ratings and Characteristic Curves

TO-251

| Ref. | Dimensions | | | | | |
|------|-------------|------|------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 2.20 | | 2.40 | 0.088 | | 0.095 |
| A2 | 0.90 | | 1.20 | 0.035 | | 0.047 |
| B | 0.55 | | 0.65 | 0.022 | | 0.026 |
| B2 | 5.10 | | 5.40 | 0.200 | | 0.213 |
| B3 | 0.76 | | 0.85 | 0.030 | | 0.033 |
| C | 0.45 | | 0.62 | 0.018 | | 0.024 |
| C2 | 0.48 | | 0.62 | 0.019 | | 0.024 |
| D | 6.00 | | 6.20 | 0.236 | | 0.244 |
| E | 6.40 | | 6.70 | 0.252 | | 0.264 |
| G | | 2.30 | | | 0.091 | |
| H | 16.0 | | 17.0 | 0.630 | | 0.669 |
| L | 8.90 | | 9.40 | 0.350 | | 0.370 |
| L1 | 1.80 | | 1.90 | 0.071 | | 0.075 |
| L2 | 1.37 | | 1.50 | 0.054 | | 0.059 |
| V1 | | 4° | | | 4° | |

Package Outline Dimensions Millimeters
TO-251S


| Symbol | Common | | |
|--------|----------|------|------|
| | mm | | |
| | Mim | Nom | Max |
| A | 2.2 | 2.3 | 2.4 |
| A1 | 0.9 | 1.0 | 1.1 |
| b | 0.66 | 0.76 | 0.86 |
| C | 0.46 | 0.52 | 0.58 |
| D | 6.50 | 6.6 | 6.7 |
| D1 | 5.15 | 5.3 | 5.45 |
| D2 | 4.6 | 4.8 | 4.95 |
| E | 10.4 | ---- | 11.5 |
| E1 | 6.0 | 6.1 | 6.2 |
| E2 | 5.400REF | | |
| e | 2.286BSC | | |
| L | 3.5 | 4.0 | 4.3 |
| L1 | 0.9 | --- | 1.27 |
| L2 | 1.4 | --- | 1.9 |